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PRIMA-SOLDER
ME8456-00

Stress Free
Reworkable
Electrically Conductive
Epoxy Paste Adhesive

IDEAL FOR:

Large Area Die
Substrate and Component
Reworkability
Mismatched CTE's

DESCRIPTION:

ME8456-00 is a reworkable, pure silver filled, electrically and thermally conductive epoxy paste adhesive. It exhibits outstanding flexibility for bonding materials having highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper).

It can be readily reworked at 80-100°C. It is ideal for applications such as large area die attach and substrate attach because of its ability to bond materials having highly mismatched CTE's.

AVAILABILITY:

ME8456-00 is available in syringes for automatic needle dispense applications or in jars. Both viscosity and thixotropic index can be modified to your specific needs.

APPLICATION PROCEDURES:

- (1) Thaw for 30 minutes before opening jar.
- (2) Dispense adhesive onto clean substrate.
- (3) Pre-bake dispensed adhesive at 60°C for 30 to 60 minutes to achieve optimum bonding. Pre-bake not needed in all applications.**
- (4) Cure according to one of the recommended schedules.

TYPICAL PROPERTIES*

Electrical Resistivity (125 °C/ 60 minute)	<4x10 ⁻⁴ ohm-cm
Dielectric Strength (Volts/mil)	N/A
Glass Transition Temp.(°C)	-20
Current Carrying Capabilities	35 Amp/mm ²
Lap-Shear Strength	>200 psi >1.4 N/mm ²
Device Push-off Strength	>1200 psi >8.3 N/mm ²
Hardness (Type)	80 (A)
Cured Density (gm/cc)	4.0
Thermal Conductivity	87 Btu-in/hr-ft ² -°F 12.5 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	120
Maximum Continuous Operation Temp. (°C)	150
Avg. Viscosity(2.5 rpm, 24°C) (Brookfield DV-1,spindle CP51)	60,000 cp

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

CURE SCHEDULES:

<u>Temperature</u>	<u>Time</u>	<u>Pressure</u>
80°C	12 hr	
100°C	6 min	(Pre-bake req
125°C	2 hr	(Pre-bake req
150°C	30 min	(Pre-bake req

** For higher temperature curing above 125°C, and/or bonding area of over 1x1 sq cm, it is recommended the dispensed adhesive be pre-baked, open-faced without parts, at 60°C for 30 minutes before parts are mounted and cured.

SHELF LIFE:

<u>Storage temperature</u>	<u>Shelf Life</u>
-40°C	1 yr
0°C	3 mo

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